

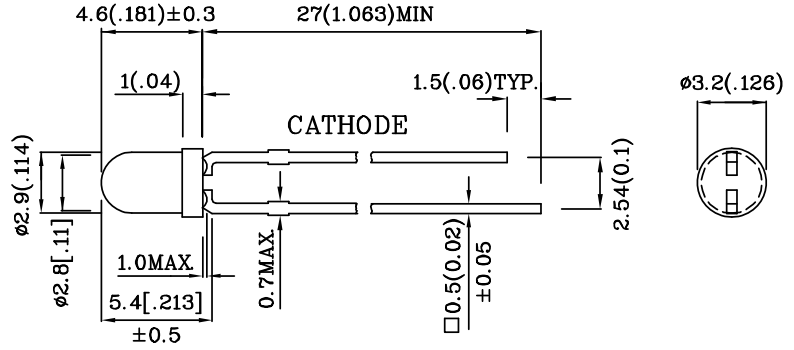
PRELIMINARY SPEC

Features

- LOW POWER CONSUMPTION.
- POPULAR T-1 DIAMETER PACKAGE.
- GENERAL PURPOSE LEADS.
- RELIABLE AND RUGGED.
- LONG LIFE-SOLID STATE RELIABILITY.
- AVAILABLE ON TAPE AND REEL.
- RoHS COMPLIANT.



**ATTENTION**  
OBSERVE PRECAUTIONS  
FOR HANDLING  
ELECTROSTATIC  
DISCHARGE  
SENSITIVE  
DEVICES



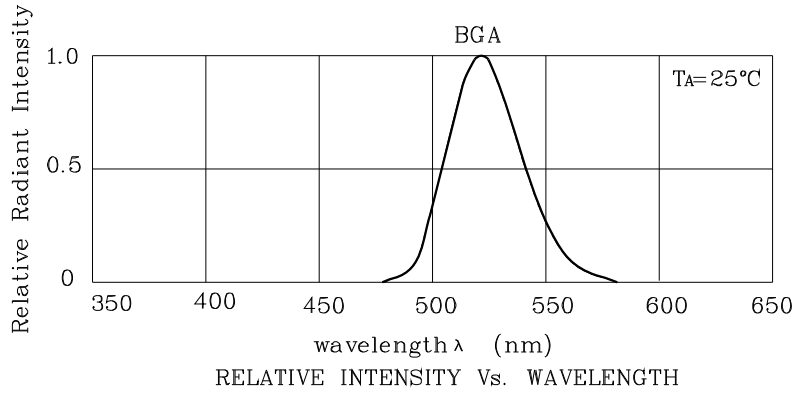
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
3. Specifications are subject to change without notice.

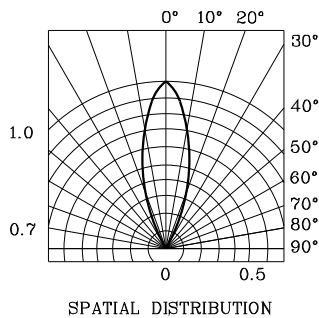
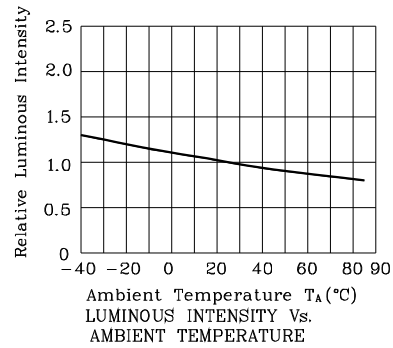
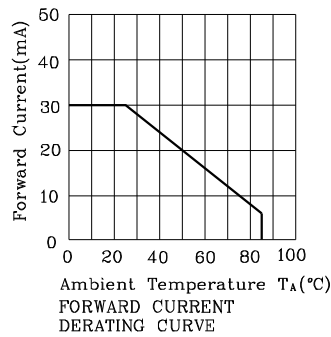
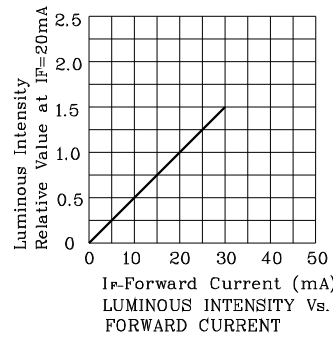
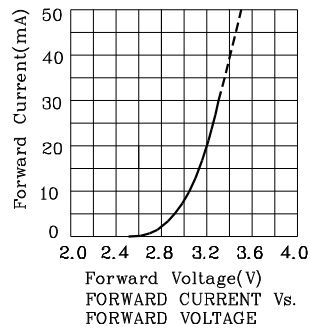
Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ )		BGA (InGaN)	Unit
Reverse Voltage	$V_R$	5	V
Forward Current	$I_F$	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{FS}$	100	mA
Power Dissipation	$P_T$	120	mW
Operating Temperature	$T_A$	-40 ~ +85	°C
Storage Temperature	$T_{stg}$	-40 ~ +85	
Electrostatic Discharge Threshold (HBM)		1000	V
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

Operating Characteristics ( $T_A=25^\circ\text{C}$ )		BGA (InGaN)	Unit
Forward Voltage (Typ.) ( $I_F=20\text{mA}$ )	$V_F$	3.2	V
Forward Voltage (Max.) ( $I_F=20\text{mA}$ )	$V_F$	4.0	V
Reverse Current (Max.) ( $V_R=5\text{V}$ )	$I_R$	10	$\mu\text{A}$
Wavelength of Peak Emission (Typ.) ( $I_F=20\text{mA}$ )	$\lambda_P$	520	nm
Wavelength of Dominant Emission (Typ.) ( $I_F=20\text{mA}$ )	$\lambda_D$	525	nm
Spectral Line Full Width At Half-Maximum (Typ.) ( $I_F=20\text{mA}$ )	$\Delta\lambda$	35	nm
Capacitance (Typ.) ( $V_F=0\text{V}$ , $f=1\text{MHz}$ )	$C$	100	pF

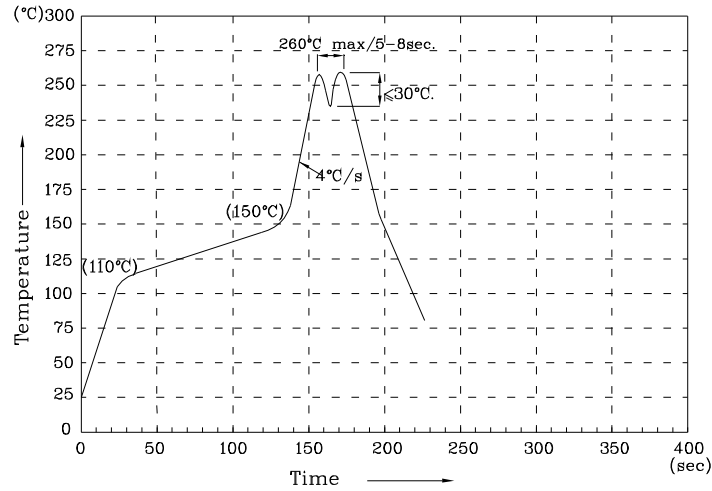
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity ( $I_F=20\text{mA}$ ) mcd	Wavelength nm $\lambda_P$	Viewing Angle $2\theta$ 1/2
				min.	typ.	
LBGA11W	Green	InGaN	Water Clear	1200	2990	520 34°



❖ BGA



Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.

Remarks:

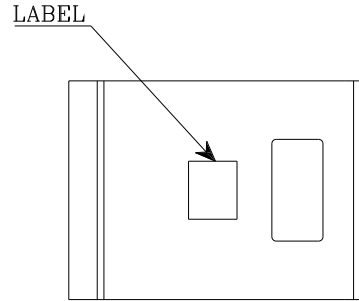
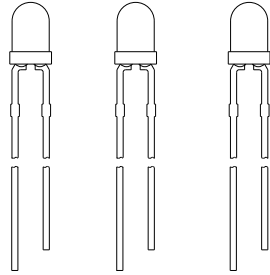
If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

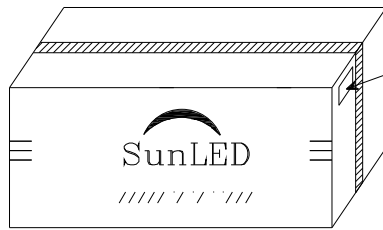
Note: Accuracy may depend on the sorting parameters.

**PACKING & LABEL SPECIFICATIONS**

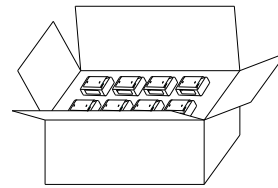
**LBGA11W**



500PCS/BAG

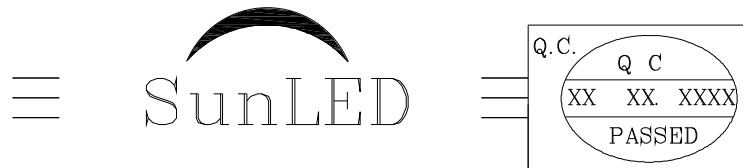



OUTSIDE LABEL



20K / BOX

10K / BOX



P/NO : Lxx11x	
QTY : 500 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 XXXXXXXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	